

SOT871-1

plastic thermal enhanced very thin quad flat package; no leads; 52 terminals; body 6 x 6 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN52
Package type industry code	HVQFN52
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-12-2004

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.9	-	6	6.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	52	-	

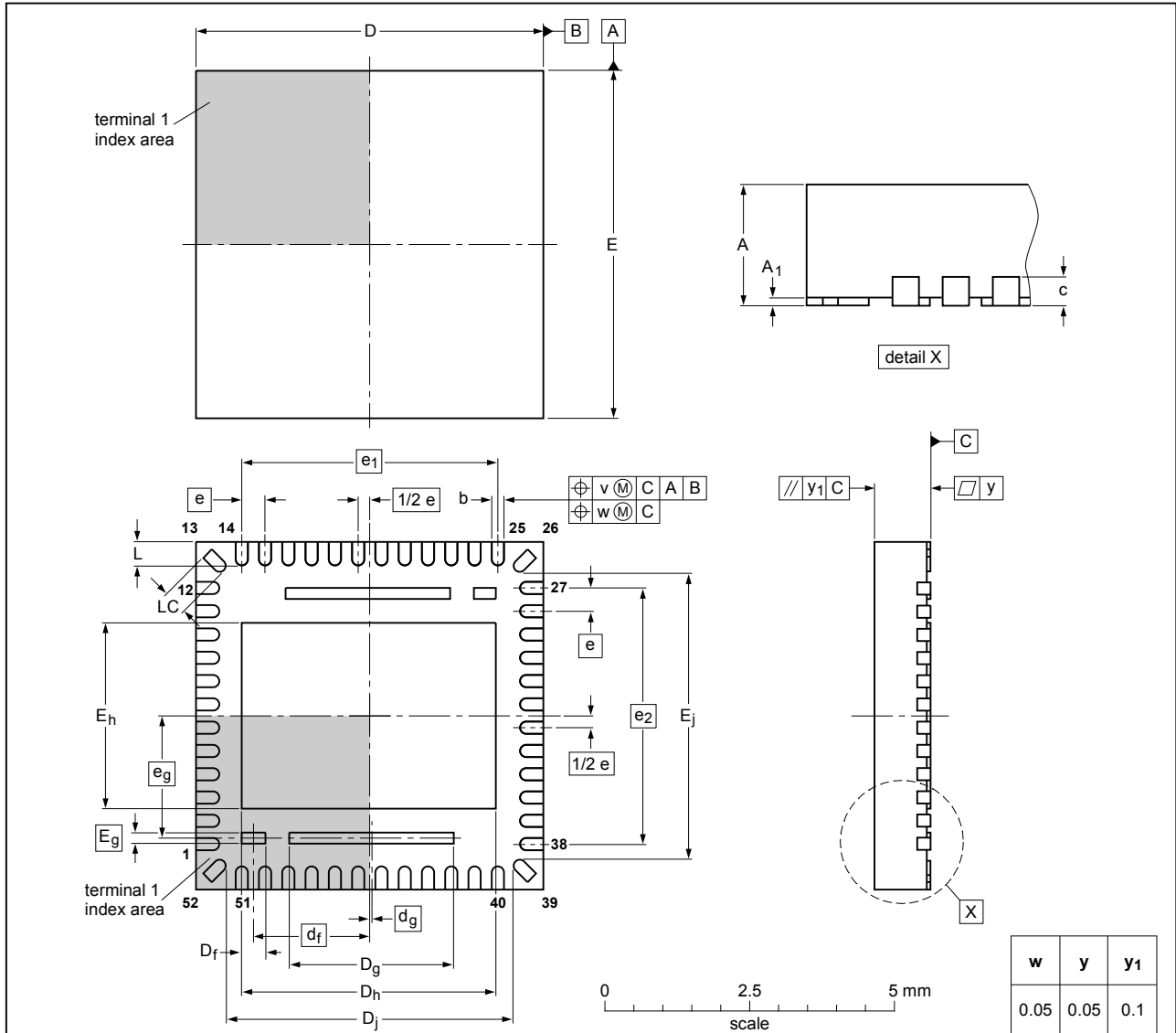


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2. Package outline

HVQFN52: plastic thermal enhanced very thin quad flat package; no leads; 52 terminals; body 6 x 6 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max	A ₁	b	c	D ⁽¹⁾	D _f	d _f	D _g	d _g	D _h	D _j	E ⁽¹⁾	E _g	e _g	E _h	E _j	e	e ₁	e ₂	L	LC	v
mm	1	0.05 0.00	0.25 0.15	0.2	6.1 5.9	0.45 0.35	2	2.9 2.8	0.02	4.55 4.25	5.05 4.95	6.1 5.9	0.25 0.15	2.1	3.35 3.05	5.05 4.95	0.4	4.4	4.4	0.5 0.3	0.45 0.35	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT871-1	---	---	---			-04-10-25- 04-12-16

Fig. 1. Package outline HVQFN52 (SOT871-1)

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3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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